

Title (en)

CURING COMPOSITION FOR AN EPOXY RESIN COMPOSITION, EPOXY RESIN COMPOSITION, AND MULTI-COMPONENT EPOXY RESIN SYSTEM WITH IMPROVED LOW TEMPERATURE CURING

Title (de)

HÄRTERZUSAMMENSETZUNG FÜR EINE EPOXIDHARZMASSE, EPOXIDHARZMASSE UND MEHRKOMPONENTEN-EPOXIDHARZSYSTEM MIT VERBESSERTER TIEFTEMPERATURHÄRTUNG

Title (fr)

COMPOSITION DE DURCISSEUR POUR RÉSINE ÉPOXYDE, RÉSINE ÉPOXYDE ET SYSTÈME DE RÉSINE ÉPOXYDE À PLUSIEURS COMPOSANTS AYANT UN MEILLEUR DURCISSEMENT À BASSE TEMPÉRATURE

Publication

EP 3962984 A1 20220309 (DE)

Application

EP 20718346 A 20200420

Priority

- EP 19171884 A 20190430
- EP 2020060954 W 20200420

Abstract (en)

[origin: CA3132925A1] The invention relates to a curing composition for a multi-component epoxy resin composition for chemically fixing construction elements, an epoxy resin composition and a multi-component epoxy resin system. The invention further relates to a method for chemically fixing construction elements in boreholes. The invention also relates to the use of a combination of a salt (S) with a phenol derivative for chemically fixing construction elements, in particular at low temperatures (= 0 °C), for improving the curing and the extraction resistance.

IPC 8 full level

C08G 59/50 (2006.01); **C08G 59/62** (2006.01); **C08G 59/68** (2006.01)

CPC (source: EP KR US)

C08G 59/50 (2013.01 - EP KR); **C08G 59/5006** (2013.01 - EP KR US); **C08G 59/5026** (2013.01 - EP KR US); **C08G 59/5033** (2013.01 - EP KR US); **C08G 59/5073** (2013.01 - EP KR US); **C08G 59/621** (2013.01 - EP KR); **C08G 59/68** (2013.01 - EP KR); **C08G 59/686** (2013.01 - EP KR); **C08G 59/687** (2013.01 - EP KR)

Citation (search report)

See references of WO 2020221608A1

Designated contracting state (EPC)

AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

Designated extension state (EPC)

BA ME

DOCDB simple family (publication)

EP 3733731 A1 20201104; AU 2020264706 A1 20210930; CA 3132925 A1 20201105; CN 113631624 A 20211109; CN 113631624 B 20231020; EP 3962984 A1 20220309; JP 2022532049 A 20220713; KR 20220002400 A 20220106; US 2022213259 A1 20220707; WO 2020221608 A1 20201105

DOCDB simple family (application)

EP 19171884 A 20190430; AU 2020264706 A 20200420; CA 3132925 A 20200420; CN 202080024898 A 20200420; EP 2020060954 W 20200420; EP 20718346 A 20200420; JP 2021564688 A 20200420; KR 20217037829 A 20200420; US 202017607021 A 20200420